Highly-accelerated temperature and humidity stress test (HAST)
EIA/JEDEC
STANDARD

Test Method A110-B

Highly-Accelerated Temperature and Humidity Stress Test (HAST)

JESD22-A110-B
(Revision of Test Method A110-A)

FEBRUARY 1999

ELECTRONIC INDUSTRIES ALLIANCE
JEDEC Solid State Technology Association
INTERNATIONAL ELECTROTECHNICAL COMMISSION

HIGHLY-ACCELERATED TEMPERATURE AND HUMIDITY STRESS TEST (HAST)

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IEC-PAS 62177 was submitted by JEDEC and has been processed by IEC technical committee 47: Semiconductor devices.

The text of this PAS is based on the following document:

This PAS was approved for publication by the P-members of the committee concerned as indicated in the following document:

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